



1.5A SURFACE MOUNT BRIDGE RECTIFIER

Product Summary (@ TA = +25°C)

V _{RRM} (V)	I _O (A)	V _F (V)	I _R (μA)
1,000	1.5	1.0	5

Features and Benefits

- Glass Passivated Die Construction
- Miniature Package Saves Space on PC Boards
- Low Leakage Current
- Ideal for SMT Manufacturing
- Low Forward Voltage Drop
- Surge Overload Rating to 70A Peak
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

Description and Applications

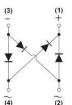
Suitable for AC to DC bridge full wave rectification for SMPS, LED lighting, adapters, battery chargers, home appliances, office equipment, and telecommunication applications.

Mechanical Data

- Case: DBF
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 (3)
- Polarity: As Marked on Body
- Weight: 0.214 grams (Approximate)



Top View



Internal Schematic

Ordering Information (Note 4)

Part Number	Compliance	Case	Packaging
DBF1510U-13	Commercial	DBF	3,000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



Marking Information



DBF1510U = Product Type Marking Code

Oli = Manufacturers' Code Marking

YMD = Date Code Marking

Y = Last Digit of Year (ex: 7 = 2017)

M = See Month/Code Table Below

D = Day 1~9 =1~9; Day 10~31= A~V

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

Maximum Ratings (@ T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	1000	V
RMS Reverse Voltage	V _{R(RMS)}	700	V
Average Rectified Output Current (Note 5) @ T _C = +110°C	lo	1.5	Α
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	70	Α
I ² t Rating for Fusing (1ms < t < 8.3ms)	l ² t	20.34	A ² S

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Ambient (Note 6) (Per Element)	$R_{\theta JA}$	50	°C/W
Typical Thermal Resistance, Junction to Case (Per Element)	Rejc	10	°C/W
Operating and Storage Temperature Range	T _{J,} T _{STG}	-55 to +150	°C

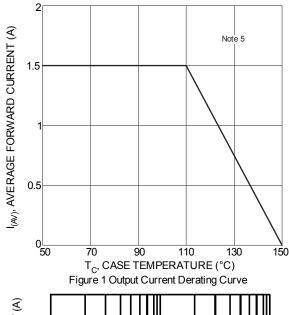
Electrical Characteristics (@ T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	$V_{(BR)R}$	1,000	_	_	V	$I_R = 5\mu A$
Forward Voltage (Per Element)	V _F		0.87 0.94	0.95 1.0	V	I _F = 0.75A, T _A = +25°C I _F = 1.5A, T _A = +25°C
Leakage Current (Note 7) (Per Element)	I _R		0.03 11	5 500	μA	V _R = 1,000V, T _A = +25°C V _R = 1,000V, T _A = +125°C
Total Capacitance (Per Element)	Ст	-	25	_	pF	V _R = 4V, f = 1.0MHz

Notes:

- 5. Device mounted on glass epoxy PC board with 1.3mm² solder pad.
- 6. Device mounted on glass epoxy substrate with 1oz/ft², 15mmx15mm copper pad per pin.
- 7. Short duration pulse test used to minimize self-heating effect.





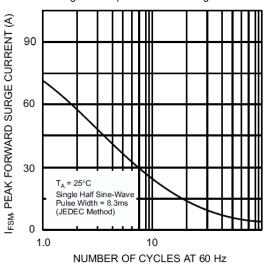
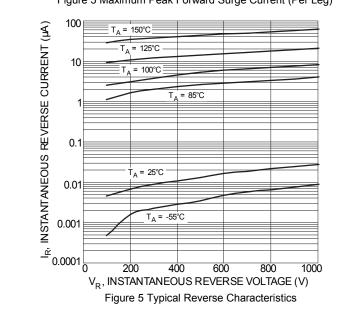
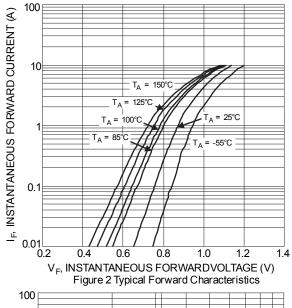


Figure 3 Maximum Peak Forward Surge Current (Per Leg)





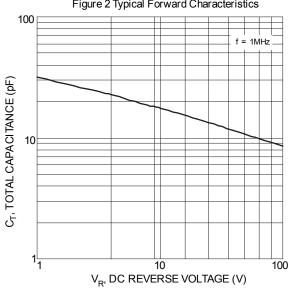


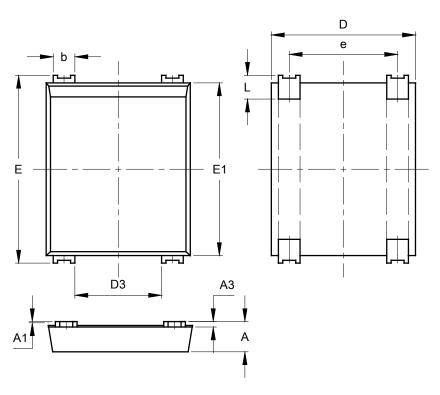
Figure 4 Total Capacitance vs. Reverse Voltage



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.



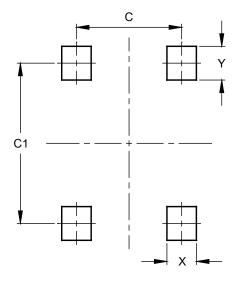


Dim	Min	Max			
Α	1.30	1.50			
A1	0.04	0.12			
A3	0.15	0.35			
b	0.80	1.20			
D	6.45	6.85			
D3	3.80	4.20			
Е	8.50 8.90				
E1	7.50 8.20				
е	4.80 5.20				
L	L 0.50 1.50				
All dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

DBF



Dimensions	Value (in mm)
C	5.00
C1	7.60
Х	1.40
V	1.60



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